	Type	Hits	Search Text	DBs	Time Stamp
				US-PGPUB;	
1				USPAT; EPO;	2004/12/03
	BRS	2	"6274924".pn.	JPO; DERWENT;	14:13
				IBM TDB	
				US-PGPUB;	
_	L			The state of the s	2004/12/03
2	BRS	3815	HAKID AGO CRID	JPO; DERWENT;	1
				IBM TDB	
				US-PGPUB;	
				HISDAT. EDO.	2004/12/03
3	BRS	465	LED adj chip and lead adj frame	JPO; DERWENT;	
				IBM TDB	
				US-PGPUB;	
		001		•	2004/12/03
4	BRS	981	wiring)	JPO; DERWENT;	
				IBM TDB	
				US-PGPUB;	
_	DDG	1/11/		USPAT; EPO;	2004/12/03
5	BRS			JPO; DERWENT;	1 '
				IBM TDB	
				US-PGPUB;	
6	DDC	0.0	LED adj chip and lead adj frame and (bent bend bending)	USPAT; EPO;	2005/01/07
0	BRS	88		JPO; DERWENT;	16:17
				IBM_TDB	
	BRS	ے دا	LED adj chip and lead adj frame same metal same (plated plating)	US-PGPUB;	
7				USPAT; EPO;	2004/12/03
'				JPO; DERWENT;	14:16
			pracing)	IBM_TDB	
	BRS		LED adj chip and lead adj frame	US-PGPUB;	
8		ורו		USPAT; EPO;	2004/12/03 14:34
			and transparent adj epoxy		
				IBM_TDB	
		1	LED adj chip and lead adj frame	•	
9	BRS	8	plating) and transparent adj	,	2004/12/03
					14:23
				IBM_TDB	
			II.KII ANI COIN CAMA IWIYA WIYAC	US-PGPUB;	
10	BRS	19	wiring) and lead adj frame and transparent adj epoxy		2004/12/03
				JPO; DERWENT;	14:23
	-			IBM_TDB	
11	BRS	1373	LED adj chip and lead adj frame same (bent bend bending)	US-PGPUB;	
				l .	2004/12/03
				JPO; DERWENT;	14:30
<u> </u>				IBM_TDB	
12	BRS	12.9	LED adj chip and lead adj frame	US-PGPUB;	0004/50/05
					2004/12/03
			same pattern	JPO; DERWENT;	14:31
L	1	L		IBM_TDB	

	Туре	Hits	Search Text	DBs	Time Stamp
13	BRS	46	LED adj chip and lead adj frame and "438"/\$.ccls.	JPO; DERWENT; IBM_TDB	2004/12/03 14:33
14	BRS	6	LED adj chip and lead adj frame and transparent adj epoxy and "438"/\$.ccls.	JPO; DERWENT;	2004/12/03 14:34
15	BRS	4	LED adj chip and lead adj frame and plating same metal and high adj reflectivity and diode and (molding mold molded) and (lead leads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 18:37
16	BRS	78	LED adj chip and lead adj frame and (bent bend bending and fold folding folded)	USPAT; EPO;	2005/01/07 16:18
17	BRS	8		USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:19
18	BRS	4	LED adj chip and lead adj frame and plating same metal and high adj reflectivity and (molding mold molded) and (lead leads) and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:20
19	BRS	29	(molding mold molded) and (lead	USPAT; EPO;	2005/01/07 16:20
20	BRS	324	438/26.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22
21	BRS	177	438/28.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22
22	BRS	229	438/33.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22
23	BRS	3.07	438/34.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22

	Type	Hits	Search Text	DBs	Time Stamp
24	BRS	86	438/35.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22
25	BRS	2786	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 16:22
26	BRS	1041	438/107.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	
27	BRS	492		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	1 ' '
28	BRS	825		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	1
29	BRS	0	U.WIL AND NOTE AND LEAD AND EXAME	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	1
30	BRS	13.2.	LED adj chip and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:39
31	BRS		LED adj chip and lead adj frame same (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:41
32	BRS	21	LEO AGI CHIN ANG (LEAG AGI	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:41
33	BRS	36	frame leadframe) same (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:47
34	BRS	258	LED and (lead adj frame leadframe) same (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO;	2005/01/07 18:47
35	BRS	156	leadframe) with (Ag Au Pd Ni Cr)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:47

	Type	Hits	Search Text	DBs	Time Stamp
36	BRS		leadframe) with (Ag Au Pd Ni Cr) and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/01/07 18:47
37	BRS	53	Cr) and electrode and (bent bend bening fold folded	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 18:48
38	BRS	57	Cr) and electrode and (bent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/07 18:48

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Day: Saturday Date: 1/8/2005 Time: 15:07:17

Inventor Name Search Result

Your Search was:

Last Name = YOON

First Name = JOON HO

S			
A 12 - 42 - 44 D		770 43	Inventor Name
Application# Patent#		Title	1
10617727 Not Issued	030 07/14/2003	METHOD OF	YOON, JOON
*:xxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx		~ ````````````````````````````````	34
		LIGHT-EMITTING DIODE	
		DEVICE	

Inventor Search Completed: No Records to Display.

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Search Another:	YOON	JOON HO
Inventor		Search

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